

Title (en)  
ELECTROLESS PLATINUM PLATING SOLUTION

Title (de)  
STROMLOSE PLATINIERUNGSLÖSUNG

Title (fr)  
SOLUTION DE PLACAGE DE PLATINE AUTOCATALYTIQUE

Publication  
**EP 3363928 A1 20180822 (EN)**

Application  
**EP 16855128 A 20160229**

Priority  
• JP 2015203809 A 20151015  
• JP 2016056047 W 20160229

Abstract (en)  
Provided is an electroless platinum plating solution that can exhibit solution stability without the use of heavy metal ions or thiol compounds and can prevent the generation of ammonia gas. The electroless platinum plating solution is characterized by comprising a water-soluble platinum compound, and one or more reducing agents selected from the group consisting of formalin, glucose, formic acid and formates. The water-soluble platinum compound is preferably one or more water-soluble platinum compounds selected from the group consisting of platinumous chloride (II), hydrogen tetrachloroplatinate (II), tetrachloroplatinate (II), platonic chloride (IV), hydrogen hexachloroplatinate (IV), hexachloroplatinate (IV), hydrogen hexahydroxoplatinate (IV), hexahydroxoplatinate (IV) and dichlorotetraammineplatinum (II). The electroless platinum plating solution preferably comprises an organic acid.

IPC 8 full level  
**C23C 18/44** (2006.01)

CPC (source: EP US)  
**C23C 18/44** (2013.01 - EP US)

Cited by  
US10941494B2

Designated contracting state (EPC)  
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Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 3363928 A1 20180822; EP 3363928 A4 20190619**; JP 2017075379 A 20170420; JP 6352879 B2 20180704; TW 201713798 A 20170416; TW I586833 B 20170611; US 2018305819 A1 20181025; WO 2017064874 A1 20170420

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**EP 16855128 A 20160229**; JP 2015203809 A 20151015; JP 2016056047 W 20160229; TW 105106086 A 20160301; US 201615767817 A 20160229